Amendments to the Specification

Please replace paragraph **[0006]** with the following amended paragraph:

**[0006]** Strap devices are typically wrapped with a piece of polymeric tape as shown in Figure 3. This tape performs several functions, including environmental protection, and can provide some protection from weld splatter. However it is known that if the bits of molten metal from the weld splatter are sufficiently hot, they can burn through the tape. Weld splatter can also directly hit the PTC element by entering the gap between the tape and the electrical lead.

Please replace paragraph **[0007]** with the following amended paragraph:

**[0007]** We have discovered that it is possible to form the metal lead of a strap device in such a way as to prevent weld splatter from contacting and potentially damaging a PTC element. An obstruction or barrier can be formed in or added to the lead in an area between the spot weld and the PTC element. This obstruction acts as a shield to prevent weld splatter from hitting the edge of the PTC element and damaging it. The obstruction could be formed in or added to the individual leads before reflow attachment to the PTC chip or could be formed in or added to the final device after assembly.

Please replace paragraph **[0012]** with the following amended paragraph:

**[0012]** The circuit protection device of the invention comprises a laminar resistive element composed of a PTC material, e.g. a conductive polymer composition or a ceramic. Such conductive polymer compositions comprise a polymeric component, and dispersed therein, a particulate conductive filler such as carbon black or metal. Conductive polymer compositions are described in U.S. Patent Nos. 4,237,441 (van Konynenburg et al.), 4,304,987 (van Konynenburg), 4,514,620 (Cheng et al.), 4,534,889 (van Konynenburg et al.), 4,545,926 (Fouts et al.), 4,724,417 (Au et al.),.4,774,024 (Deep et al.), 4,935,156 (van Konynenburg et al.), 5,049,850 (Evans et al.), 5,378,407 (Chandler et al.), 5,451,919 (Chu et al.), 5,582,770 (Chu et al.), 5,747,147 (Wartenberg et al.), and 5,801,612 (Chandler et al.), and U.S. Patent Applications Nos. 09/364,504 (Isozaki et al., filed July 30, 1999), now U.S. Patent No. 6,358,438, and 09/387,275 (Chen et al., filed August 31, 1999), now U.S. Patent No. 6,362,721. The disclosure of each of these patents and applications is incorporated herein by reference. Conductive polymer compositions are preferred due to lower resistivity and easier manufacturability than ceramic compositions.

Please replace paragraph **[0015]** with the following amended paragraph:

**[0015]** Devices of the invention comprise first and second laminar electrodes, preferably metal foil electrodes, with the laminar conductive polymer resistive element sandwiched between them so that the first electrode is secured to the first face of the laminar element, i.e. the first major surface, and the second electrode is secured to the second face of the laminar element, i.e. the second major surface. Particularly suitable foil electrodes have at least one surface that is microrough, e.g. electrodeposited, preferably electrodeposited nickel or copper. Appropriate electrodes are disclosed in U.S. Patents Nos. 4,689,475 (Matthiesen), 4,800,253 (Kleiner et al.), and 5,874,885 (Chandler et al.) and copending U.S. Application No. 08/816,471 (Chandler et al., filed March 13, 1997), now U.S. Patent No. 6,570,483, the disclosure of each of which is incorporated herein by reference. The electrodes may be attached to the resistive element by compression-molding, nip-lamination, or any other appropriate technique. The electrodes may be secured directly to the resistive element or attached by means of an adhesive or tie layer. For some devices it is preferred that the first and second laminar electrodes comprise metal layers formed by directly depositing metal onto the PTC resistive element, e.g. by plating, sputtering, or chemical deposition.

Please replace paragraph **[0028]** with the following amended paragraph:

**[0028]** Figure 9 is a device in which the barrier portion on first and second leads 21,31 is created by bending the leads. Figure 10 shows this device in cross-section along line X-X of Figure 9. In Figure 11, the first and second barriers 29,39 are in the form of a wall or dam applied to or formed as part of first and second leads 21,31, respectively. Figure 12 shows in perspective, and Figure 13 in cross-section, a device in which first and second barriers 29,39 are raised cut-outs, prepared by stamping or otherwise cutting the first and second leads.